

Fig. 1 consists of two cross-sectional views, (a) and (b), of a semiconductor device. Both views show two main substrate assemblies, 14 and 12, connected by a central component.

In view (a), the top substrate assembly 14 includes layers 1, 3, 5, 17, and 19. The bottom substrate assembly 12 includes layers 2, 6, 18, 19, and 20. A spring-like component 11 connects the two assemblies at a contact point C. A cross-hatched layer 3 is also shown on the right side of assembly 12.

In view (b), the top substrate assembly 14 is identical to view (a). The bottom substrate assembly 12 is also identical. However, the central connecting component is a chain-like structure 13. The contact point C is also indicated in view (b).